The listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-29 (Canceled)

30 (New) A radio on a single IC chip, comprising.

an antenna section for transmitting and receiving a plurality of high frequency signals,

a down-conversion section, coupled to said antenna section, for down-converting a first high frequency signal of said plurality of high frequency signals,

a bandpass filter coupled to the down-conversion section,

an up-conversion section, coupled to said antenna section, for up-converting an information signal to a seond high frequency signal of said plurality of high frequency signals; and

a shaping filter coupled to an input of said up-conversion

31. (New) The radio of claim 30, wherein said up-conversion section and said down-conversion section comprise a single variable controlled oscillator

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- 32. (New) The radio of claim 31, wherein said single variable controlled oscillator is integrated into said single IC chip.
- 33. (New) The radio of claim 32, wherein single variable controlled oscillator comprises at least one resonator.
- 34 (New) The radio of claim 30, wherein the transmission and the reception of said plurality of high frequency signals is performed in accordance with a time-division duplex mode.
- 35. (New) The radio of claim 30, wherein said down-conversion section down-converts at least one of said plurality of high frequency signals to at least one low intermediate frequency signal.
- 36. (New) The radio of claim 35, further comprising a discriminator coupled to said bandpass filter for detecting a received data signal from said at least one low intermediate frequency signal, wherein said discriminator is integrated into said single IC chip.
- 37 (New) The radio of claim 30, wherein said down-conversion section, said bandpass filter, said up-conversion section, and said shaping filter are integrated into said single IC chip, wherein bandpass filtering operations are performed by components integrated into said single IC chip